

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Electrical Characteristics (TA = 25°C, unless otherwise specified)				
Characteristic	Symbol	B250AF	B260AF	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	50	60	V
Working Peak Reverse Voltage	V _{RWM}			
DC Blocking Voltage	V _{RM}			
Average Rectified Output Current	I _O	2		A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	50		A

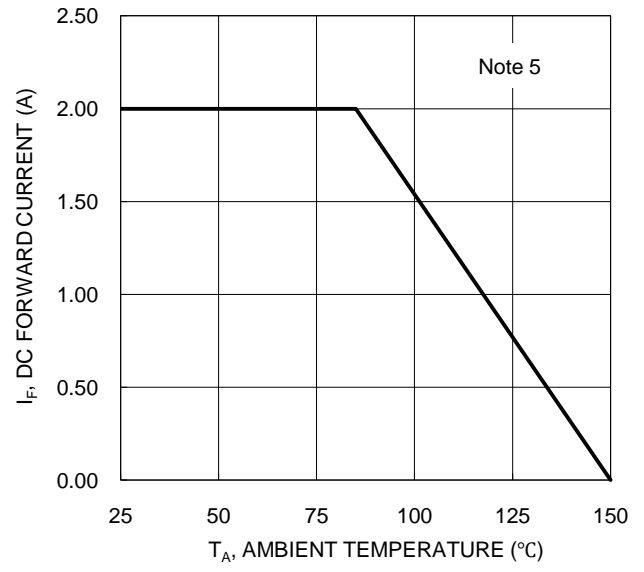
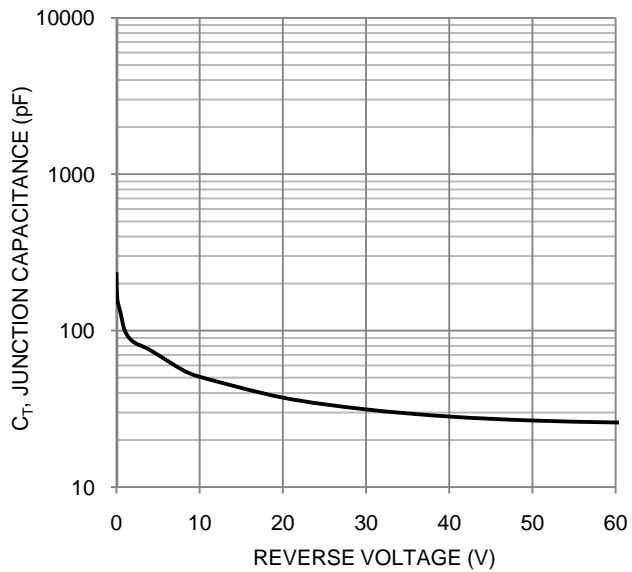
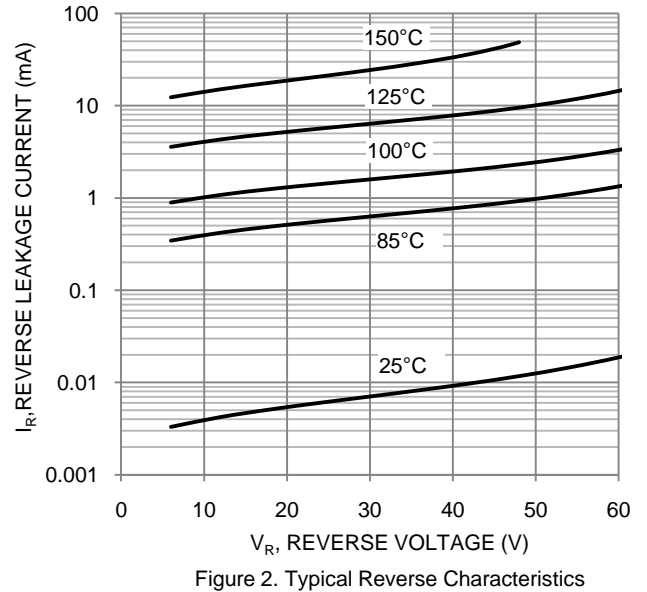
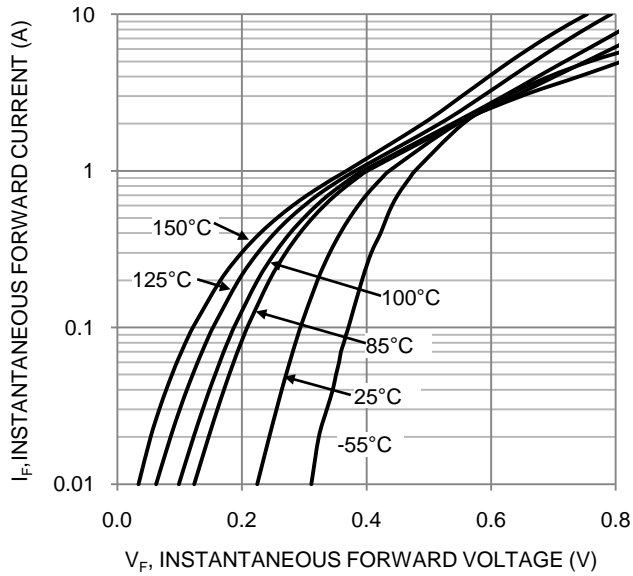
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{θJA}	95	°C/W
Typical Thermal Resistance Junction to Case (Note 5)	R _{θJC}	45	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V _F	—	0.55 0.52	0.65 —	V	I _F = 2A, T _J = +25°C I _F = 2A, T _J = +125°C
Leakage Current (Note 6)	I _R	—	0.015 0.02 15	0.10 0.20 —	mA	V _R = 50V, T _J = +25°C V _R = 60V, T _J = +25°C V _R = 60V, T _J = +125°C
Typical Capacitance	C _T	—	80	—	pF	V _R = 4.0V, f = 1MHz

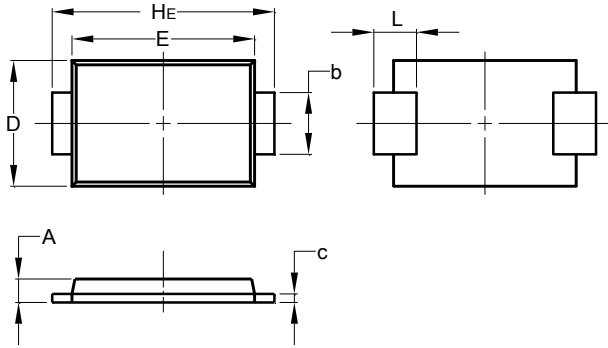
Notes: 5. Device mounted on FR-4 substrate, 0.4" x 0.5", 2oz, single-sided, PC boards with 0.2" x 0.25" copper pad.
6. Short duration pulse test used to minimize self-heating effect.



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SMAF

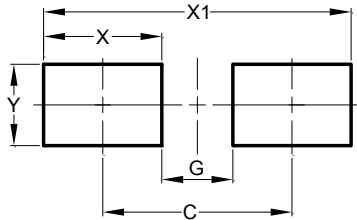


SMAF		
Dim	Min	Max
A	0.90	1.10
b	1.25	1.65
c	0.10	0.40
D	2.25	2.95
E	3.95	4.60
H_E	4.80	5.60
L	0.50	1.50
All Dimensions in mm		

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SMAF



Dimensions	Value (in mm)
C	4.00
G	1.50
X	2.50
X1	6.50
Y	1.70

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